

30V N-Channel NexFET™ Power MOSFET

FEATURES

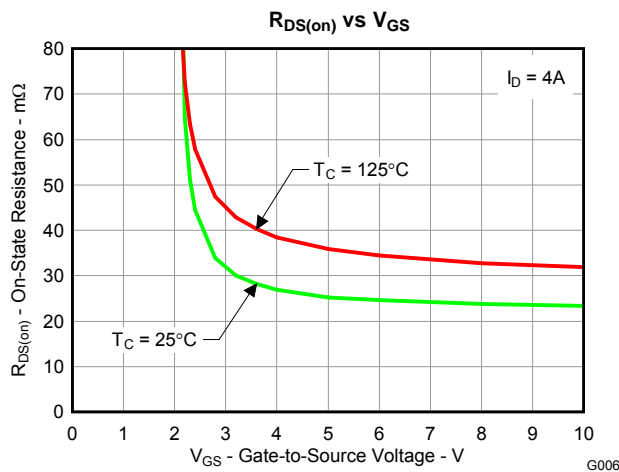
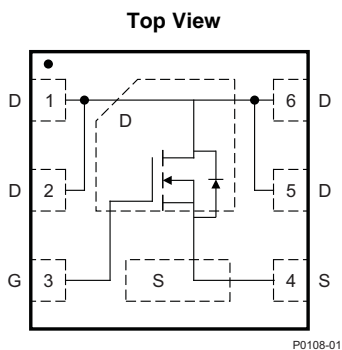
- Optimized for 5V Gate Drive
- Ultra Low Q_g and Q_{gd}
- Low Thermal Resistance
- Pb Free
- RoHS Compliant
- Halogen Free
- SON 2-mm x 2-mm Plastic Package

APPLICATIONS

- DC-DC Converters
- Battery and Load Management Applications

DESCRIPTION

The NexFET power MOSFET has been designed to minimize losses in power conversion applications and optimized for 5V gate drive applications. The 2-mm x 2-mm SON offers excellent thermal performance for the size of the package.



PRODUCT SUMMARY

V_{DS}	Drain to Source Voltage	30	V
Q_g	Gate Charge Total (4.5V)	2.1	nC
Q_{gd}	Gate Charge Gate to Drain	0.4	nC
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 3V$	31 mΩ
		$V_{GS} = 4.5V$	26 mΩ
		$V_{GS} = 8V$	24 mΩ
$V_{GS(th)}$	Threshold Voltage	1.3	V

ORDERING INFORMATION

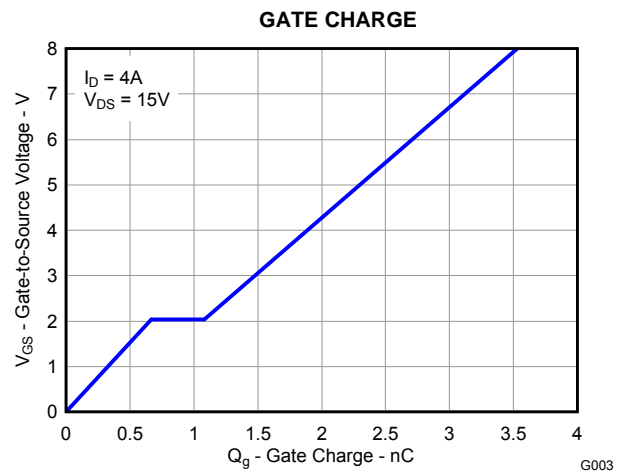
Device	Package	Media	Qty	Ship
CSD17313Q2	SON 2-mm x 2-mm Plastic Package	13-Inch Reel	3000	Tape and Reel

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$ unless otherwise stated		VALUE	UNIT
V_{DS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	+10 / -8	V
I_D	Continuous Drain Current, $T_C = 25^\circ\text{C}$	5	A
	Continuous Drain Current ⁽¹⁾	5	A
I_{DM}	Pulsed Drain Current, $T_A = 25^\circ\text{C}$ ⁽²⁾	20	A
P_D	Power Dissipation	2.3	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
E_{AS}	Avalanche Energy, Single Pulse, $I_D = 19A, L = 0.1\text{mH}, R_G = 25\Omega$	18	mJ

(1) Package Limited

(2) Pulse duration $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise stated)

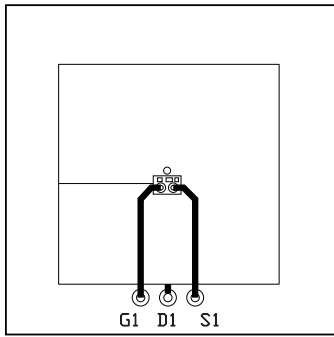
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Static Characteristics						
V_{DSS}	Drain to Source Voltage	$V_{GS} = 0V, I_D = 250\mu A$	30			V
I_{DSS}	Drain to Source Leakage	$V_{GS} = 0V, V_{DS} = 24V$			1	μA
I_{GSS}	Gate to Source Leakage	$V_{DS} = 0V, V_{GS} = +10 / -8V$			100	nA
$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.9	1.3	1.8	V
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 3V, I_D = 4A$		31	42	$m\Omega$
		$V_{GS} = 4.5V, I_D = 4A$		26	32	$m\Omega$
		$V_{GS} = 8V, I_D = 4A$		24	30	$m\Omega$
g_{fs}	Transconductance	$V_{DS} = 15V, I_D = 4A$		16		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0V, V_{DS} = 15V,$ $f = 1MHz$		260	340	pF
C_{oss}	Output Capacitance			140	180	pF
C_{rss}	Reverse Transfer Capacitance			13	17	pF
R_G	Series Gate Resistance			1.3	2.6	Ω
Q_g	Gate Charge Total (4.5V)	$V_{DS} = 15V,$ $I_D = 4A$		2.1	2.7	nC
Q_{gd}	Gate Charge – Gate to Drain			0.4		nC
Q_{gs}	Gate Charge Gate to Source			0.7		nC
$Q_{g(th)}$	Gate Charge at V_{th}			0.3		nC
Q_{oss}	Output Charge		$V_{DS} = 13.5V, V_{GS} = 0V$		3.8	
$t_{d(on)}$	Turn On Delay Time	$V_{DS} = 15V, V_{GS} = 4.5V,$ $I_D = 4A, R_G = 2\Omega$		2.8		ns
t_r	Rise Time			3.9		ns
$t_{d(off)}$	Turn Off Delay Time			4.2		ns
t_f	Fall Time			1.3		ns
Diode Characteristics						
V_{SD}	Diode Forward Voltage	$I_{SD} = 4A, V_{GS} = 0V$		0.85	1	V
Q_{rr}	Reverse Recovery Charge	$V_{DD} = 13.5V, I_F = 4A,$ $di/dt = 300A/\mu s$		6.4		nC
t_{rr}	Reverse Recovery Time			12.9		ns

THERMAL CHARACTERISTICS

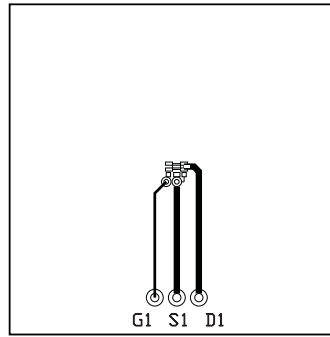
($T_A = 25^\circ\text{C}$ unless otherwise stated)

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Thermal Resistance Junction to Case ⁽¹⁾			7.4	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ⁽¹⁾⁽²⁾			67	$^\circ\text{C/W}$

- (1) $R_{\theta JC}$ is determined with the device mounted on a 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu pad on a 1.5-inch x 1.5-inch (3.81-cm x 3.81-cm), 0.06-inch (1.52-mm) thick FR4 PCB. $R_{\theta JC}$ is specified by design, whereas $R_{\theta JA}$ is determined by the user's board design.
- (2) Device mounted on FR4 material with 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu.



Max $R_{\theta JA} = 67^{\circ}\text{C/W}$
when mounted on
1 inch² (6.45 cm²) of 2-
oz. (0.071-mm thick)
Cu.



Max $R_{\theta JA} = 228^{\circ}\text{C/W}$
when mounted on a
minimum pad area of
2-oz. (0.071-mm thick)
Cu.

TYPICAL MOSFET CHARACTERISTICS

($T_A = 25^{\circ}\text{C}$ unless otherwise stated)

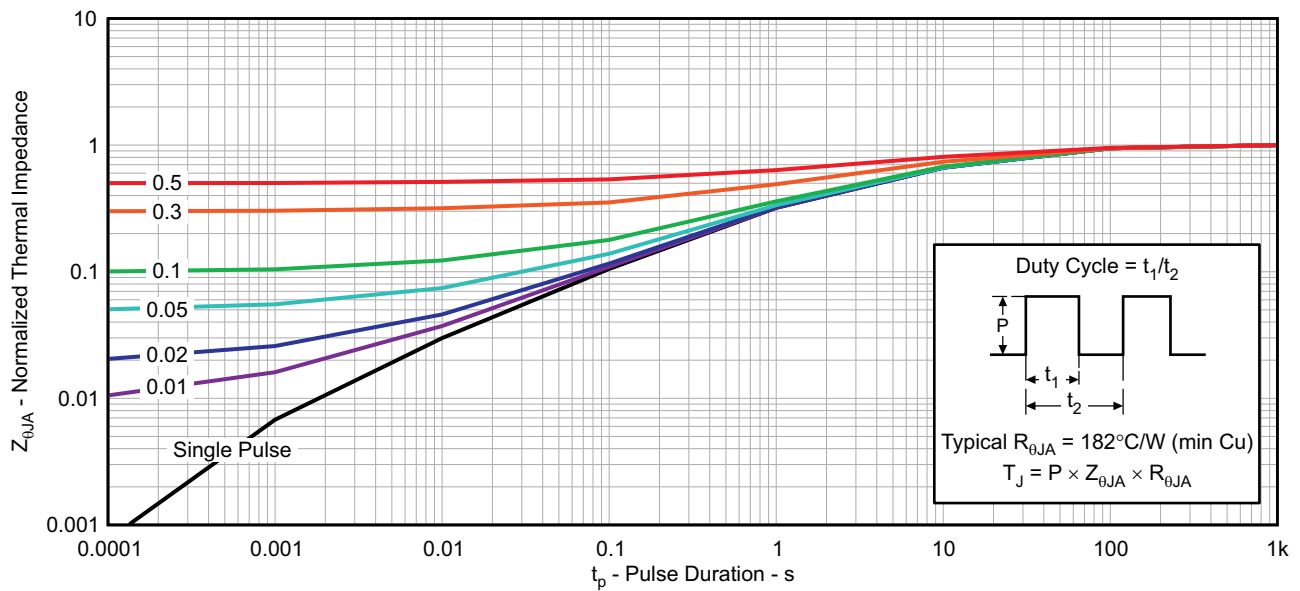
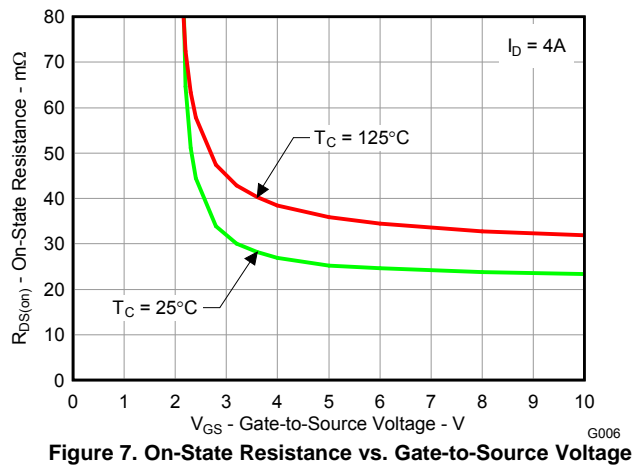
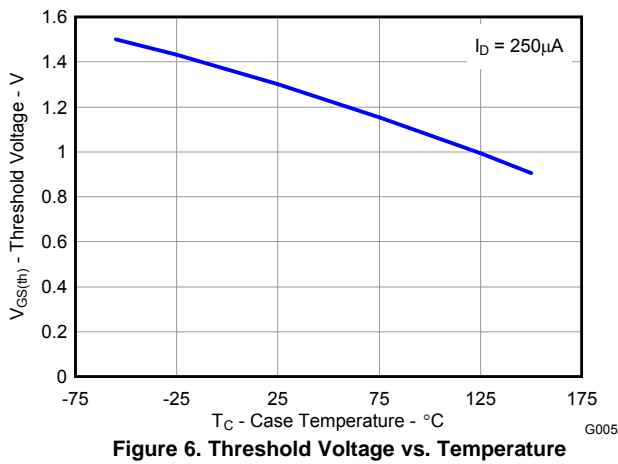
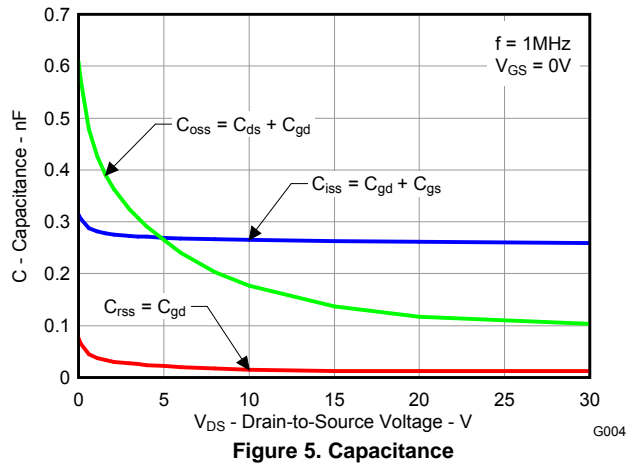
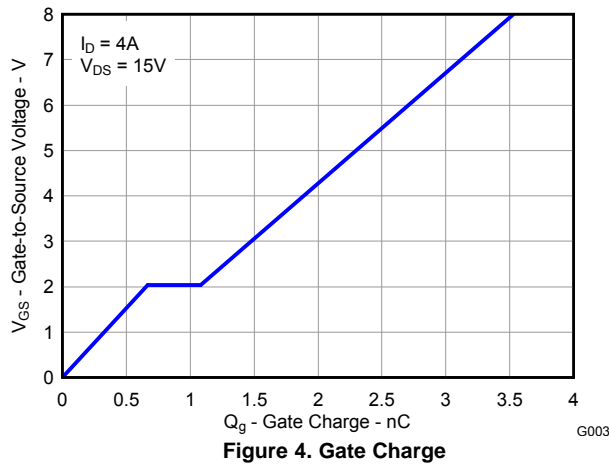
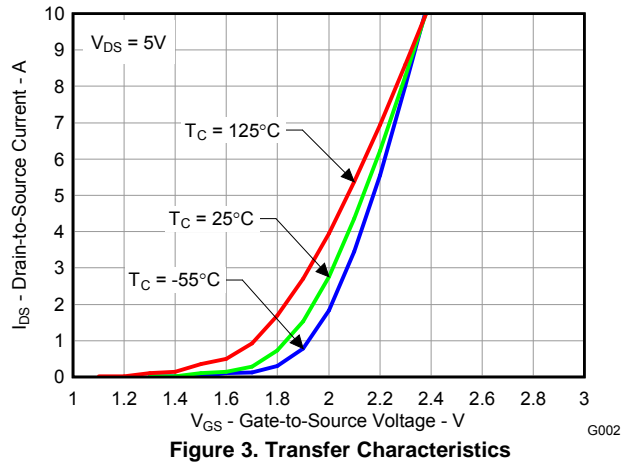
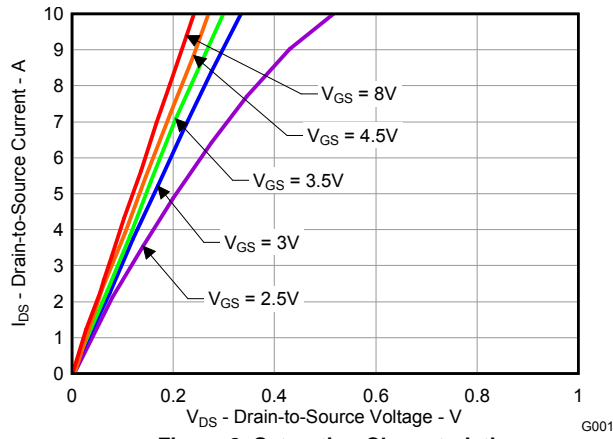


Figure 1. Transient Thermal Impedance

TYPICAL MOSFET CHARACTERISTICS (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)



TYPICAL MOSFET CHARACTERISTICS (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)

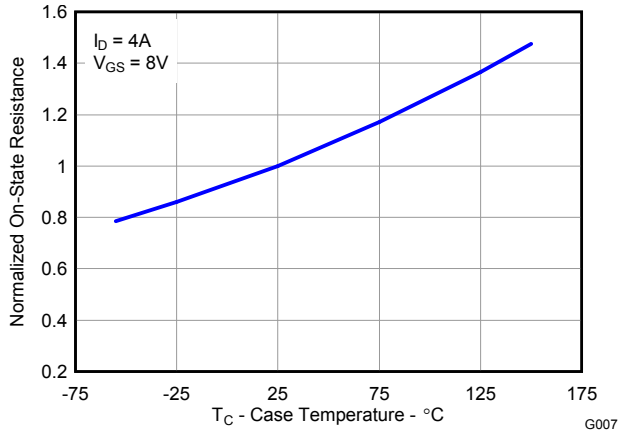


Figure 8. Normalized On-State Resistance vs. Temperature

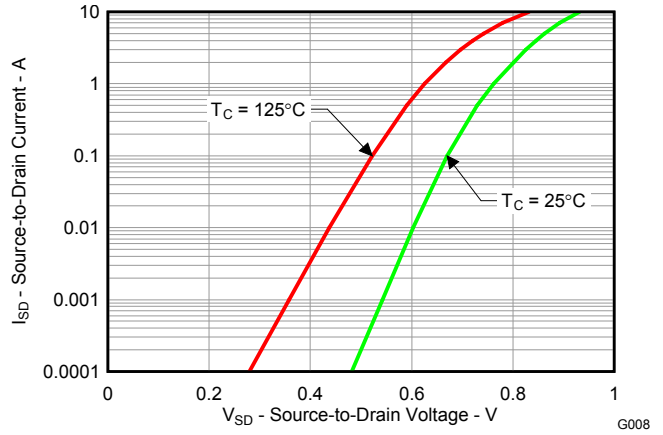


Figure 9. Typical Diode Forward Voltage

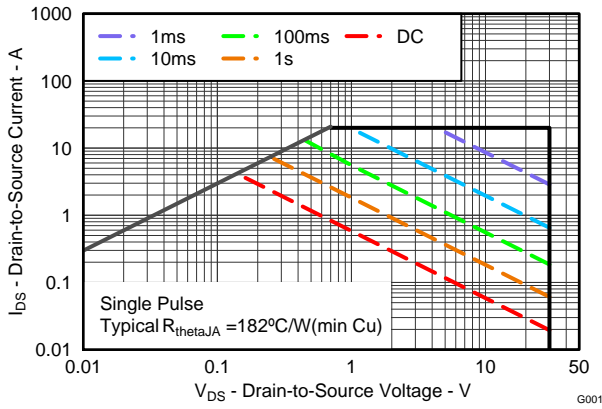


Figure 10. Maximum Safe Operating Area

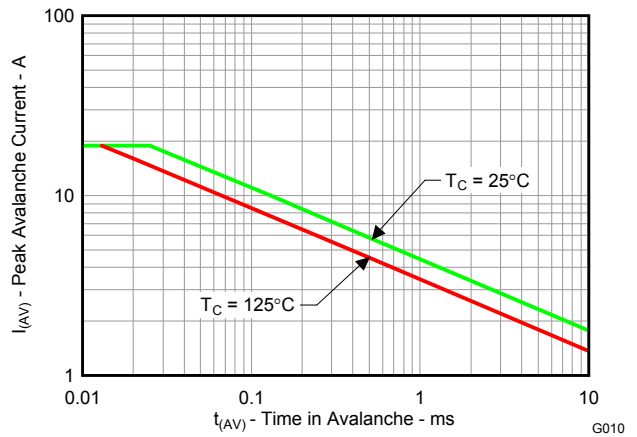


Figure 11. Single Pulse Unclamped Inductive Switching

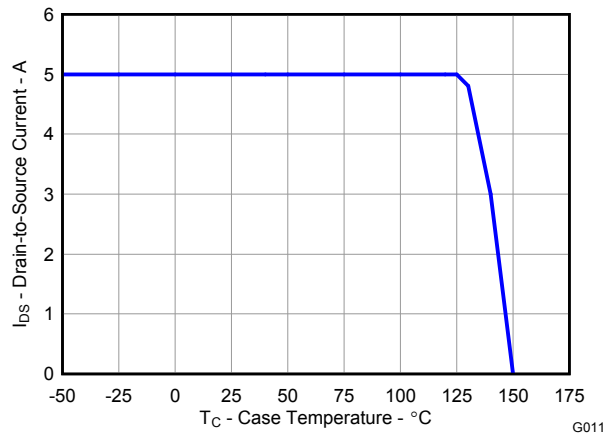
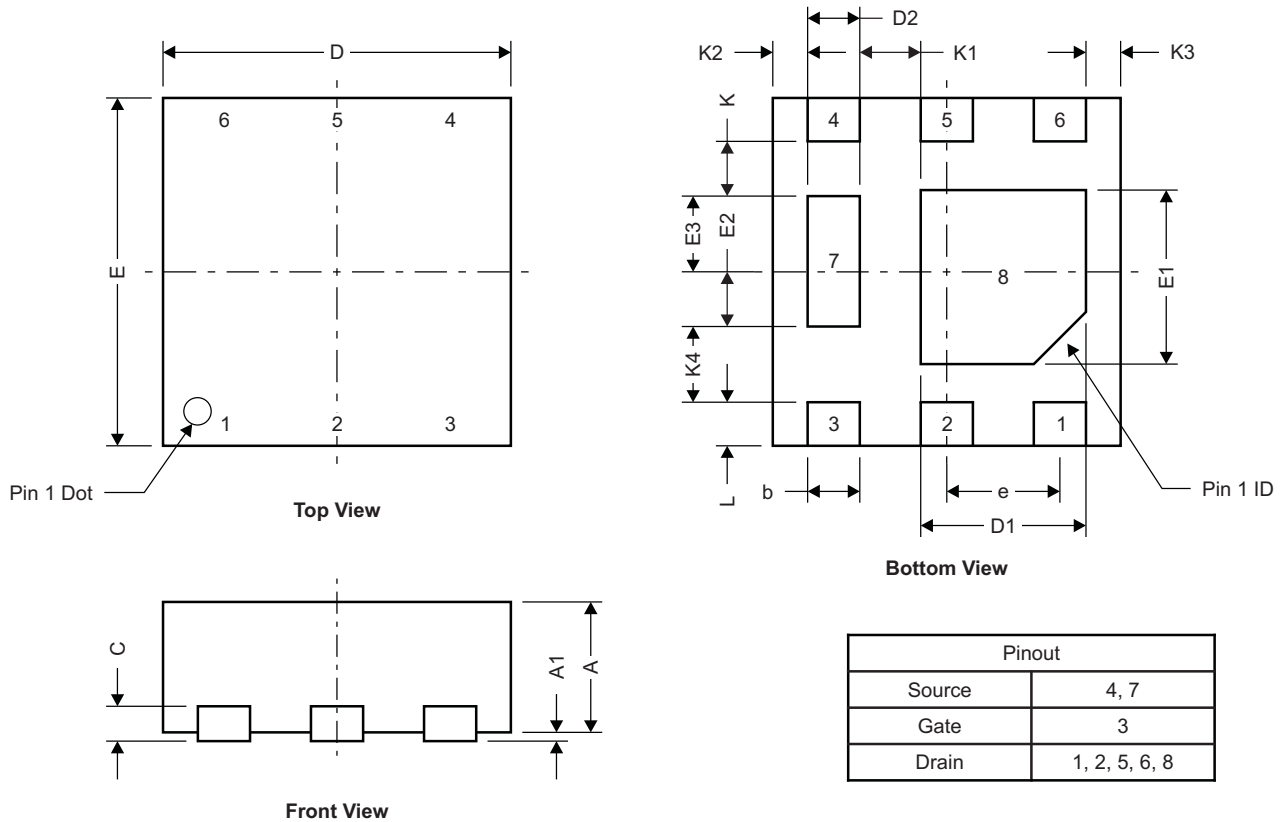


Figure 12. Maximum Drain Current vs. Temperature

MECHANICAL DATA

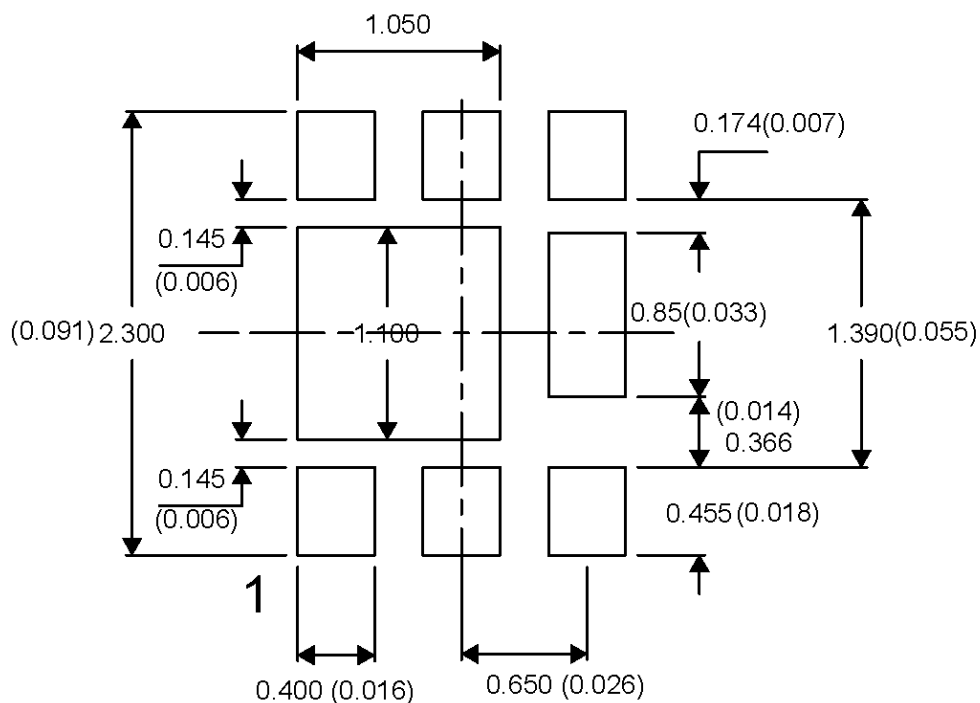
Q2 Package Dimensions



M0175-02

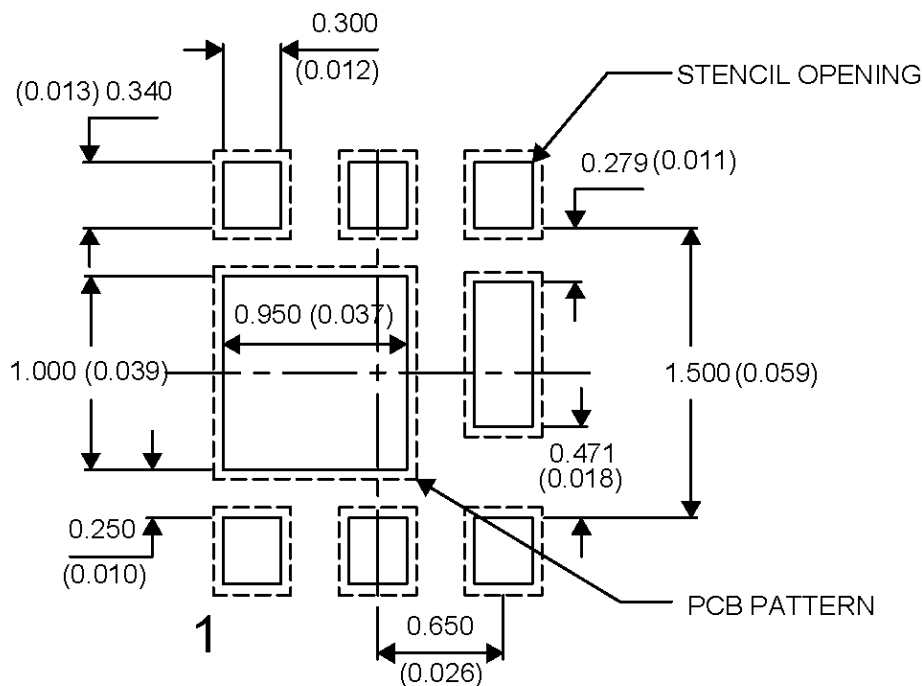
DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.700	0.750	0.800	0.028	0.030	0.032
A1	0.000		0.050	0.000		0.002
b	0.250	0.300	0.350	0.010	0.012	0.014
C	0.203 TYP			0.008 TYP		
D	2.000 TYP			0.080 TYP		
D1	0.900	0.950	1.000	0.036	0.038	0.040
D2	0.300 TYP			0.012 TYP		
E	2.000 TYP			0.080 TYP		
E1	0.900	1.000	1.100	0.036	0.040	0.044
E2	0.280 TYP			0.0112 TYP		
E3	0.470 TYP			0.0188 TYP		
e	0.650 BSC			0.026 TYP		
K	0.280 TYP			0.0112 TYP		
K1	0.350 TYP			0.014 TYP		
K2	0.200 TYP			0.008 TYP		
K3	0.200 TYP			0.008 TYP		
K4	0.470 TYP			0.0188 TYP		
L	0.200	0.25	0.300	0.008	0.010	0.012

Recommended PCB Pattern



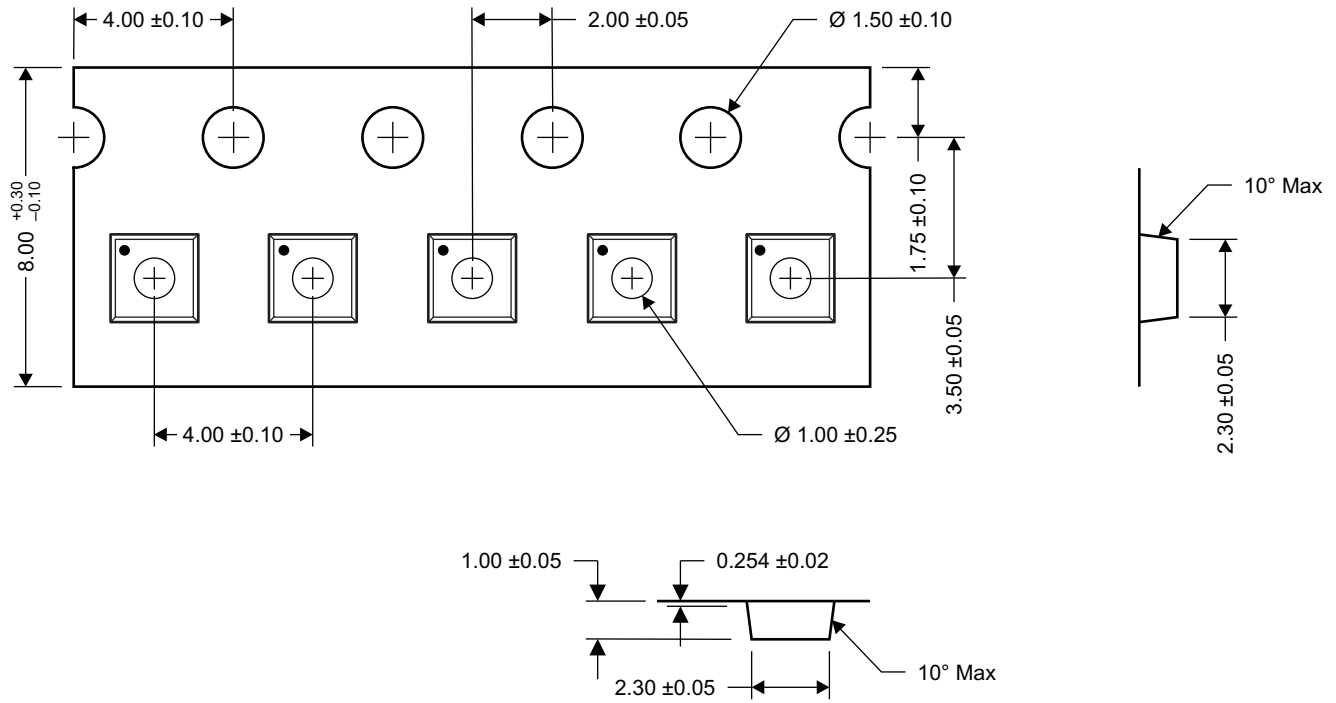
For recommended circuit layout for PCB designs, see application note [SLPA005](#) – Reducing Ringing through PCB Layout Techniques.

Recommended Stencil Pattern



Note: All dimensions are in mm, unless otherwise specified.

Q2 Tape and Reel Information



- Notes:
1. Measured from centerline of sprocket hole to centerline of pocket
 2. Cumulative tolerance of 10 sprocket holes is ± 0.20
 3. Other material available
 4. Typical SR of form tape Max 10^8 OHM/SQ
 5. All dimensions are in mm, unless otherwise specified.

M0168-01

REVISION HISTORY

Changes from Original (March 2010) to Revision A	Page
<ul style="list-style-type: none"> • Changed Q_{rr} - Reverse Recovery Charge From: 10.2 nC To: 6.4 nC 2 	2
Changes from Revision A (March 2010) to Revision B	Page
<ul style="list-style-type: none"> • Deleted the Package Marking Information section 8 	8
Changes from Revision B (October 2010) to Revision C	Page
<ul style="list-style-type: none"> • Changed the Recommended PCB Pattern 7 • Added the Recommended Stencil Pattern 7 	7
Changes from Revision C (January 2013) to Revision D	Page
<ul style="list-style-type: none"> • Changed Figure 10, Maximum Safe Operating Area 5 	5

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CSD17313Q2	WSON	DQK	6	3000	180.0	8.4	2.3	2.3	1.0	4.0	2.3	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CSD17313Q2	WSON	DQK	6	3000	550.0	455.0	55.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com